



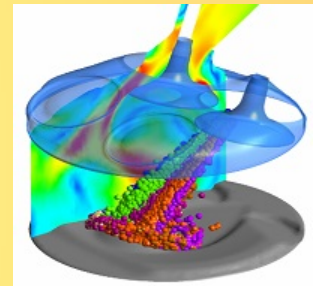
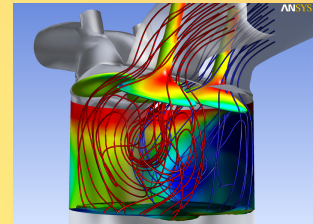
Engineering Simulation Integration at Top Engineering and Research Programmes

Introduction

In today's highly competitive engineering world, numerous trends have emerged. Increasing power density of electronic devices, product miniaturization across industries, consumer demand for smart products, escalating material costs and increased emphasis on sustainability — have created special challenges. These forces have created a multi physical phenomena that makes single physics simulation alone not so reliable as it once was. As a result, multiphysics simulation is now an imperative.

ANSYS Multiphysics capabilities offers the perfect solution set to simulate the interaction among structural mechanics, heat transfer, fluid flow and electromagnetics all within a single unified simulation platform for solving today's complex design challenges.

Join us for this seminar to learn how you can fully benefit from ANSYS Multiphysics which is the new revolution in engineering.



Who Should Attend

Professors, Curriculum Planners, Researchers, Students

Presenter Profile



Dr Vincent Chai is currently a technical sales engineer at CAD-IT Consultants and is part of the technical and sales team that support customers in various disciplines and domains. He graduated from NTU with a Ph.D. degree in Mechanical and Aerospace Engineering, where his thesis is focused on flapping wings aerodynamics (experimental and numerical simulation study) for unmanned vehicles. He has worked as a project officer for DSTA project on debris flight analysis and Research engineer from NIDEC Singapore.

Event Information

Date : 3rd August 2015 (Monday)
Time : 2:00 pm - 3:00 pm
Venue : NTU LT 12

[Register NOW](#)

Register online for this FREE event.

CAD-IT Consultants reserves the right to cancel or postpone the event due to unforeseen circumstances.

For enquiries, please call 6508-7575 or email at caditevents@cadit.com.sg